ADVANCED METALIZATION

Call for Papers

ADMETA 2026

Advanced Metallization Conference 2026: 35th Session

Oct. 7, 2026: Tutorial (Japanese only) | Oct. 8–9, 2026: Conference
Online-Onsite Hybrid Conference

Theme: "AI Enablers: Exploring the Frontiers of Advanced Interconnect and Packaging Technologies"
General Chair: Noriaki Matsunaga (Applied Materials Japan)
Sponsorship by the Japan Society of Applied Physics

ADMETA has built a long history and made significant contributions to the development of interconnect technologies that support advanced semiconductor devices. This year marks the memorable 35th ADMETA conference. As a dedicated international conference on interconnects and packaging, ADMETA covers a wide range of fields related to materials, processes, equipment, devices, circuit design, integration, measurement, assembly, and packaging. The theme for 2026 is "AI Enablers: Exploring the Frontiers of Advanced Interconnect and Packaging Technologies." Under this theme, we invite researchers and engineers from industry, government, and academia to share original results and discuss emerging challenges and opportunities for AI-era semiconductors.

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★ Technical Sessions

- **Atomic Layer Process (Focused Session)**
- **Materials Science and Technology**
- **Advanced Dry and Wet Processes**
- **Advanced Interconnects**
- **Advanced Packaging I**
- **Advanced Packaging II**

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★ Scope and Topics

Advanced Interconnect Technology

- **Materials & Processes**
  New materials, Metal, Alloy, Dielectrics, Low-k, High-k, SAMs, Topological semi-metal, 2D material, Graphene, Carbon nanotube, PVD, CVD, ALD, SOD, Plating, CMP, Supercritical Fluid, Reflow, Material Informatics, Cheminformatics
- **Integration & Reliability**
  Metallization, Etching, Lithography, NIL, EBDW, FSAV, Semi-damascene, Advanced Patterning, Pattern Transfer, Cleaning, Barrier Metal, Contact, Air Gap, Hard Mask, Parasitic Capacitance, EM, SIV, TDDB, Defect Detection and Analysis, Failure Mechanism and Modeling
- **Device, Architecture & MEMS**
  BEOL Transistor, MRAM, PCRAM, ReRAM, Optical interconnect, Wireless interconnect, Carbon based interconnect, Sensor, Flexible Electronics, Energy Harvesting
- **Metrology**
  Failure Analysis, 3DAP, CD-SEM, DLS, EBSD, EDS/EDX, EELS, Ellipsometer, ESCA/XPS, FIB, FT-IR, LEED/RHEED, LFA/TDTR, OBIRCH, ARPES/HAXPES/PES, Photoluminescence, Positron Annihilation, Raman, RBS/HFS, SIMS, SPM, STEM/TEM, STM, TDS, TXRF, XAFS, XRD, XRR, XRT

http://www.admeta.org/

ADVANCED METALIZATION

Advanced Packaging

- **Materials & Processes**

  Bonding Interface Dielectric/other Materials, Bonding Pad metallization, Bonding, Thinning/Planarization, Trimming, TSV, Revealing, Warpage/TTV Control, Heat dissipation, Gap filling, Organic/Inorganic RDL, Advanced core materials, Sealing/Molding

- **Integration & Reliability**

  Cu-Cu hybrid bonding, CoW, WoW, nano/high-aspect TSV, Heterogeneous Integration

- **Device, Architecture & Photonics**

  HBM, HBF, 3D stacked logic, interposer, RDL, organic or glass core substrate, CPO, EIC/PIC (Waveguide, Diffraction grating, Modulator, Photodetector), Active and Passive devices (Regulator, Bridge, Capacitor, Inductor, Resistor), 2.xD/3D Arch., Power distribution Arch., Thermal dissipation Arch.

- **Metrology**

  Hi & Precise Stacks TTV, Alignment, Void measurement, Stress, and Thermal Analysis

★ To Apply

• Prepare an extended abstract in A4 format (up to 2 pages). Figures and tables are recommended but not required.

• Presentation style: Oral (15 min talk + 5 min Q&A) or Poster (format to be announced).

• Abstract submission: The Abstract Submission site is open.

• Abstract submission deadline: June 19, 2026 (UTC-7)

• Please indicate the session/topic category and the corresponding author's contact information (mailing and e-mail addresses).

• Notification of acceptance will be announced via the secretariat/website. journals.

Contact: ADMETA 2026 Secretariat | E-mail: jimukyoku@admeta.org

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★ JJAP Special Issue

Authors with papers presented at ADMETA 2026 are encouraged to submit original manuscripts to a dedicated Special Issue of the Japanese Journal of Applied Physics (JJAP). Detailed instructions and deadlines will be announced on the ADMETA website.

★ Reminder

As the Special Issue manuscripts must be original papers, please avoid submitting identical contents to other journals.

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★ Conference Sessions (Oct. 8-9, 2026 | in English)

1) Atomic Layer Process (Focused Session)
2) Materials Science and Technology
3) Advanced Dry and Wet Processes
4) Advanced Interconnects
5) Advanced Packaging I
6) Advanced Packaging II

★ Tutorial (Oct. 7, 2026 | in Japanese)

Tutorial details will be announced on the ADMETA website. The official language of the tutorial lectures is Japanese.

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http://www.admeta.org/

★ Contact: ADMETA 2026 Secretariat

E-mail: jimukyoku@admeta.org

Website: https://www.admeta.org/

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